

ABSTRACT OF THE DISCLOSURE

5 A connecting strength at a bonding site between a wiring layer 1c and a conductor 1d is enhanced by comparing a bonding strength between a wiring layer 14 provided by covering the conductor 1d on an insulating base 1a and the conductor 1d with a bonding strength between the wiring layer 1c and the insulating base 1a in an adjacency of the conductor to set the latter relatively lower.